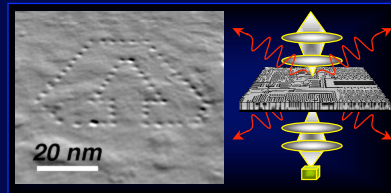


Performance of a High Count Rate Silicon Drift X-ray Detector on The ANL 300 KV AAEM



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Office of Science - BES Program
US Department of Energy

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Why are we still working on XEDS systems?

Modern nanoscale characterization using x-ray energy dispersive spectroscopy in the Analytical Electron Microscope is limited by a number of factors

- Foremost among these is the inability of an investigator to detect all characteristic x-ray emission from the region of interest of the specimen.
- Experimental operating condition of the microscope dictate the physics of the generation of x-ray emission from the sample
- To maximize sensitivity of the technique, only improvements in the detector can accomplish this task. This improvements can be achieved by optimizing the detector to maximize the :
 1. the subtending solid angle of the collected x-rays
 2. the conversion (detection) efficiency for x-rays
 3. the count rate (pulse) efficiency

ANL Applications

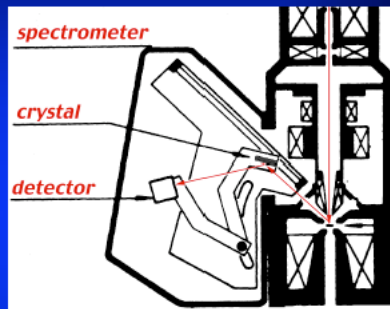
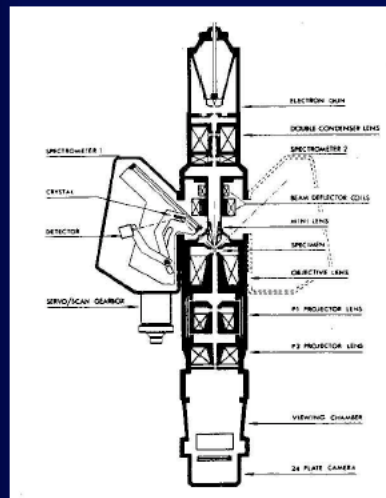
- DoE TEAM Project : Next Generation Medium Voltage FEG AEM's...
Aberration correction increase probe current!
- Scanning Confocal Electron Microscopy

Others:

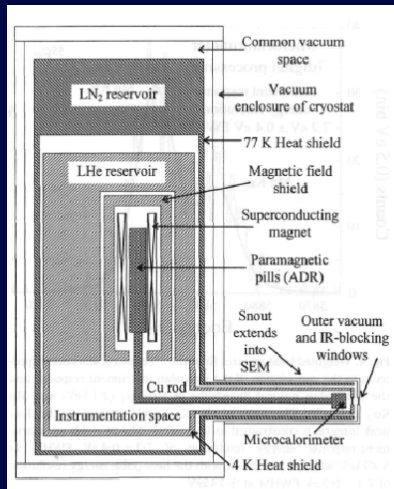
Conventional BULK specimen SEM data (Mapping)
Conventional FEG AEM TEM's

X-ray Detector Systems for the AEM

- Wavelength Dispersive Spectrometers (WDS)
- Energy Dispersive Spectrometers (EDS)
 - Si(Li) Detectors
 - HPGe Detectors
- Superconducting Calorimeters/Bolometers
- Silicon Drift Detectors



Installation of a Crystal Spectrometer in a
TEM - EMMA-4 System

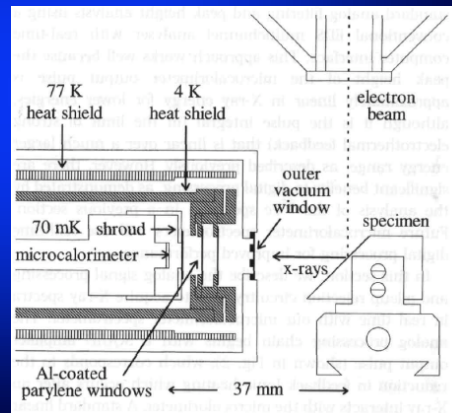


Microcalorimeter Solid Angle

$$\Omega = A/R^2$$

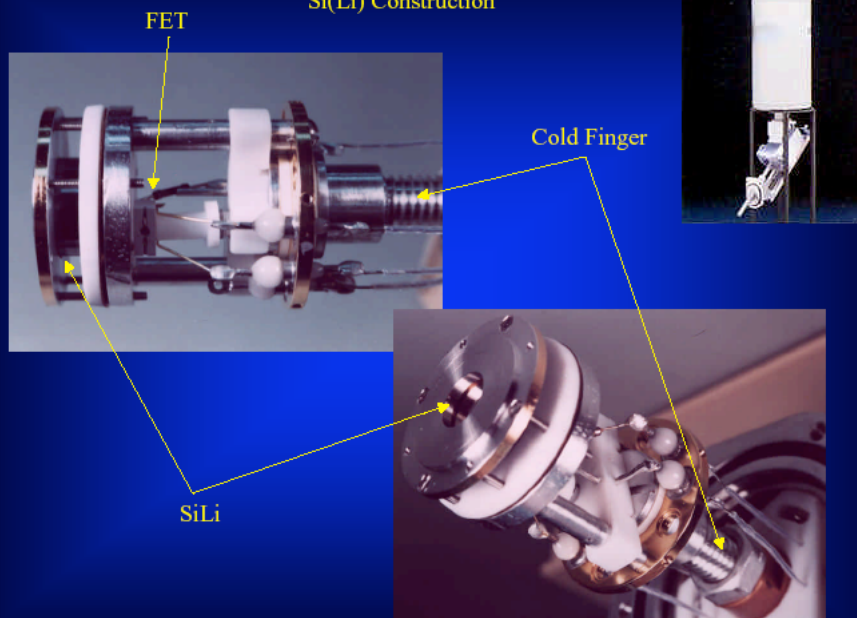
$$= (0.5 \times 0.5 \text{ mm}) / (37 \text{ mm})^2$$

$$= 0.00018 \text{ sr}$$



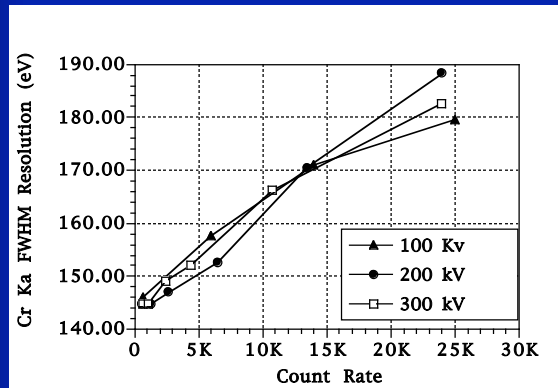
Courtesy of D. Newbury

Si(Li) Construction

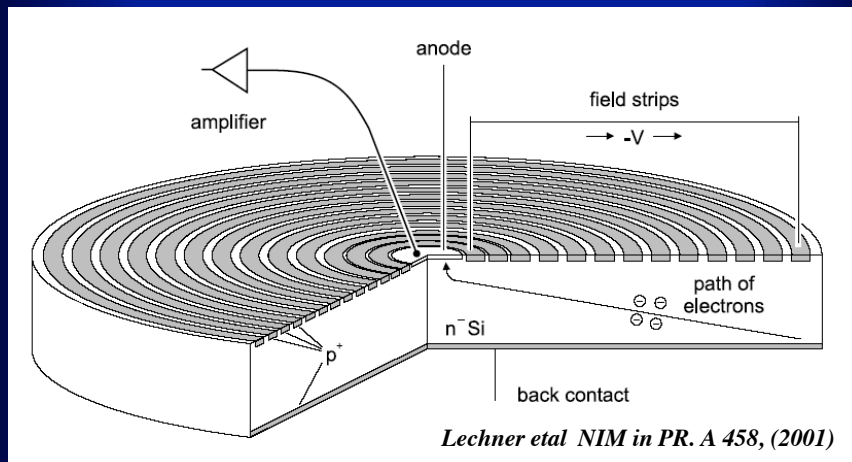


Components of a Std Si(Li)

Resolution Loss with Count Rate

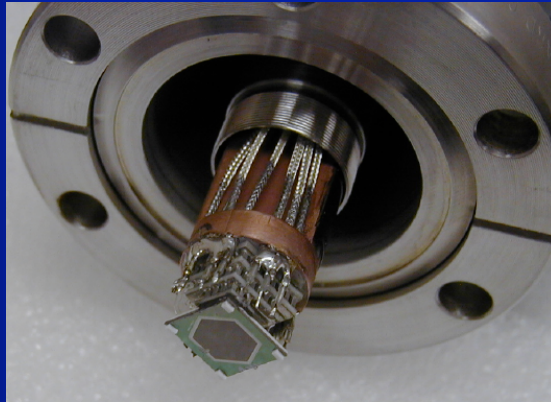


Silicon Drift Detector Construction



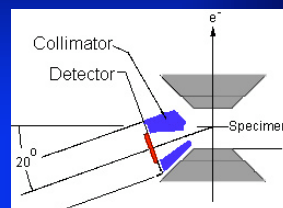
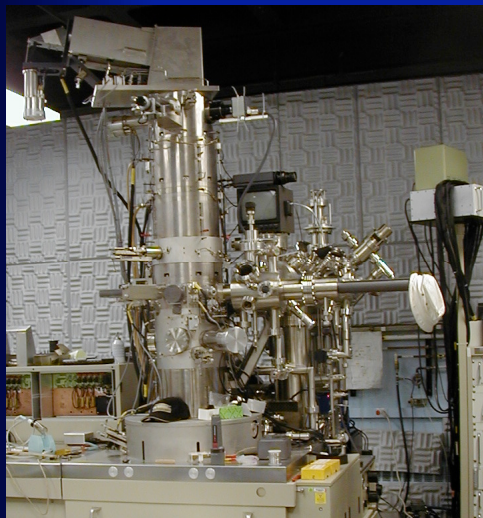
Thinner devices -> Low Capacitance -> High Count Rates

Silicon Drift Detector Construction

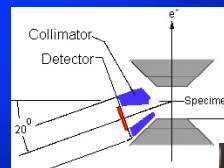
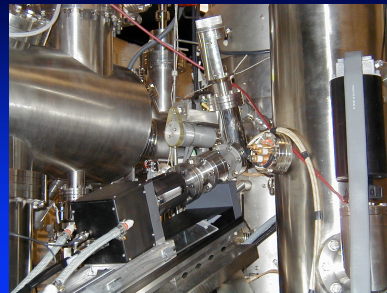
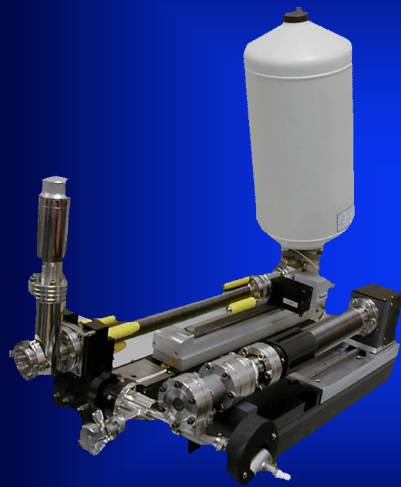


Detector Area = 50 mm²
Peltier Cooled -> No LN₂
Low Capacitance (250 fF)-> High Count Rates

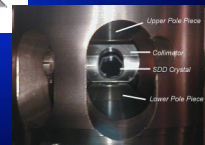
ANL Experimental Configuration



Silicon Drift Detector Construction

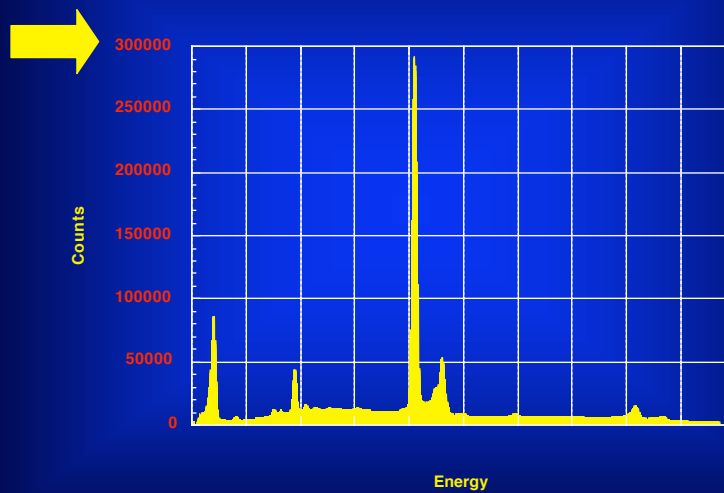


ANL ~ 0.41 sr



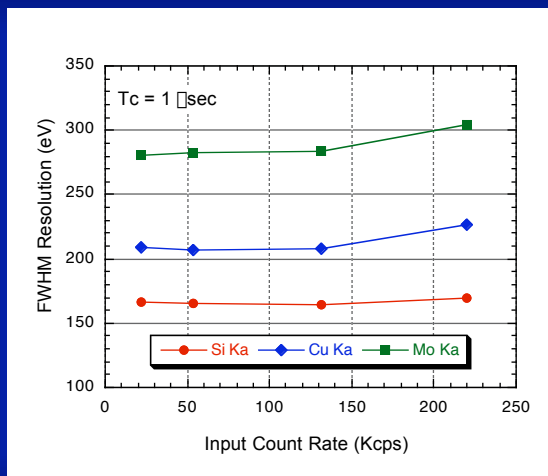
Comparison: Stnd vs SDD
LN2 dewar vs Peltier Cooler

Count Rate = ~ 200 Kcps
Time = 100 sec
Integral = 50, 000, 000 counts !

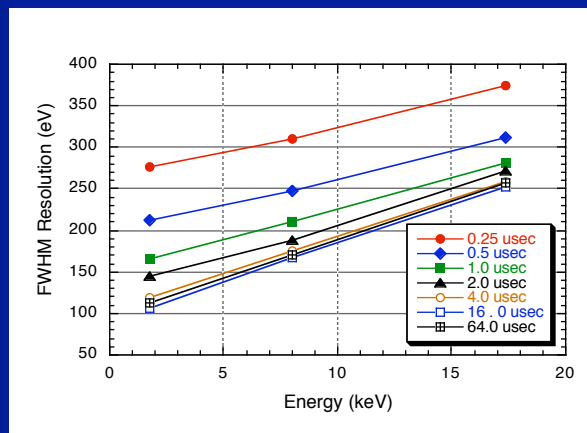


Mo-Si/Cu Slot Grid

Resolution vs Count Rate

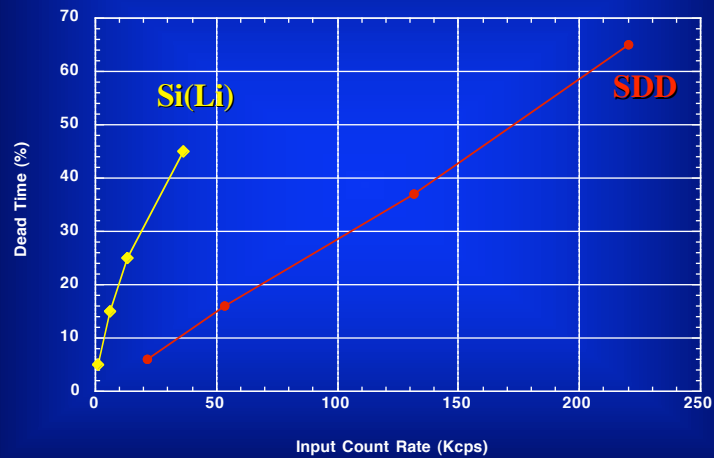


Resolution vs Time Constant

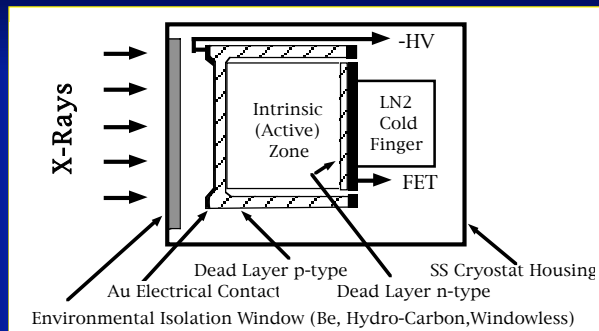


Dead Time vs Count Rate

Comparing SDD vs Si(Li) @ $E_0 = 300 \text{ keV}$



Solid State Detector Construction



Relative Detection Efficiency

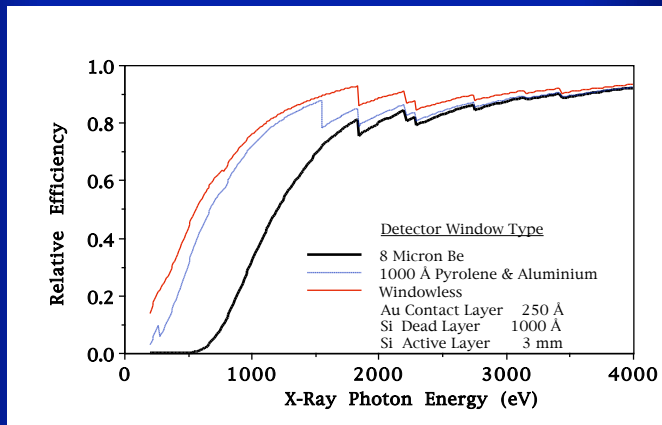
Solid State Detectors: Si(Li) or Intrinsic (High Purity) Ge

Using a simple absorption model define the relative detector efficiency $\epsilon(E)$ by the following procedure:

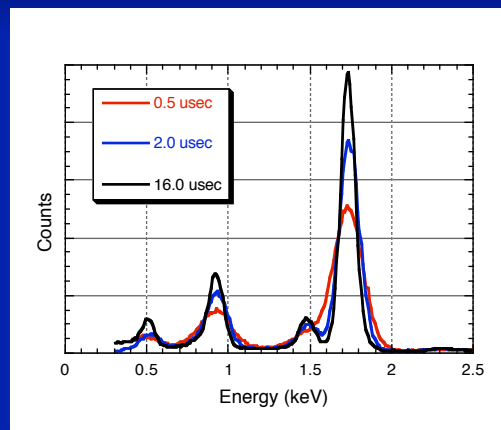
The diagram shows a detector of thickness x with incident intensity I_0 and transmitted intensity I_T . The relationship is given by the exponential absorption law:

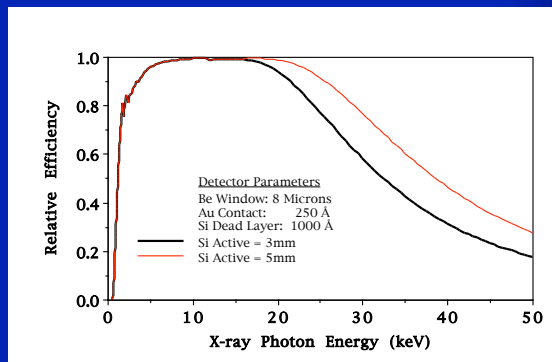
$$I_T = I_0 \exp(-\mu x) = I_0 \exp\left(-\left[\frac{\mu}{\rho}\right] \rho x\right)$$

Relative Detector Efficiency

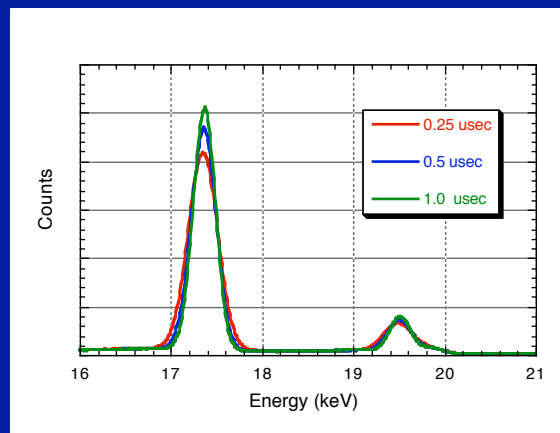


Resolution vs Tc and Energy

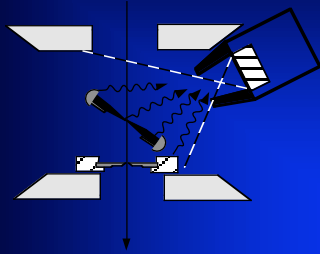




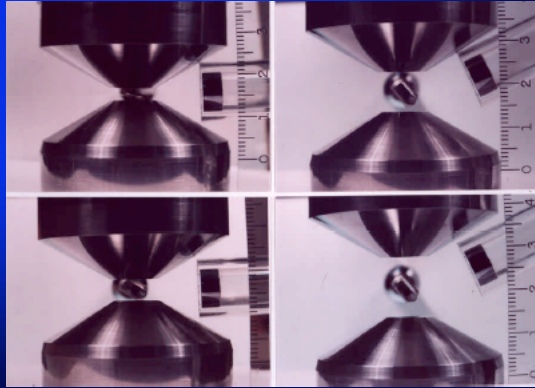
Resolution vs Tc and Energy



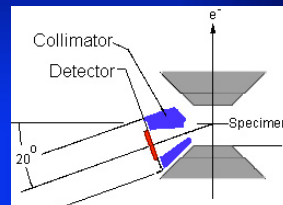
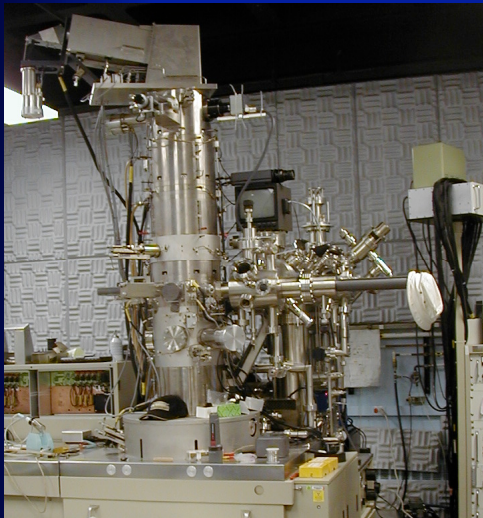
Subtending Solid Angle



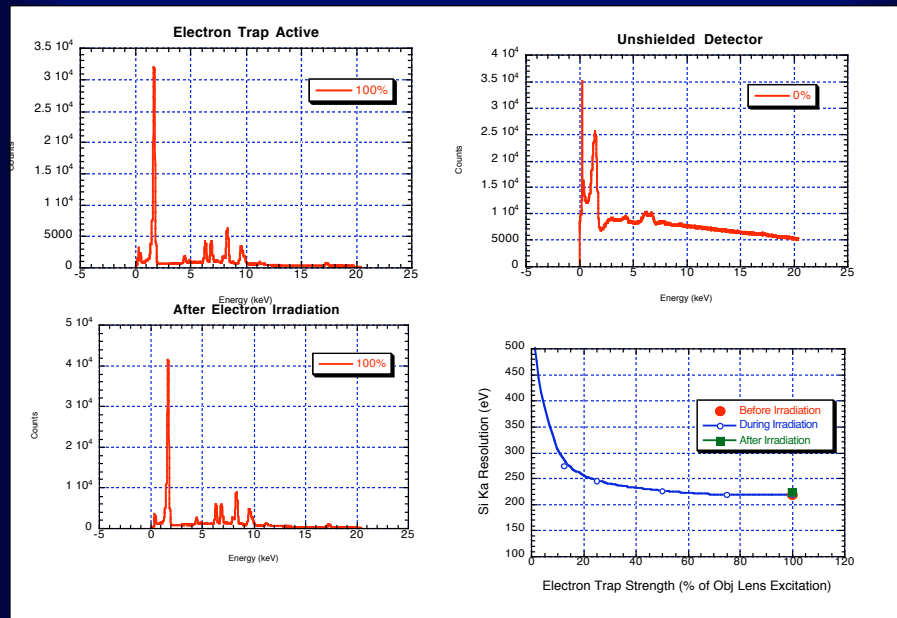
Large Solid Angles
Are Important for the
Next Generation of AEM



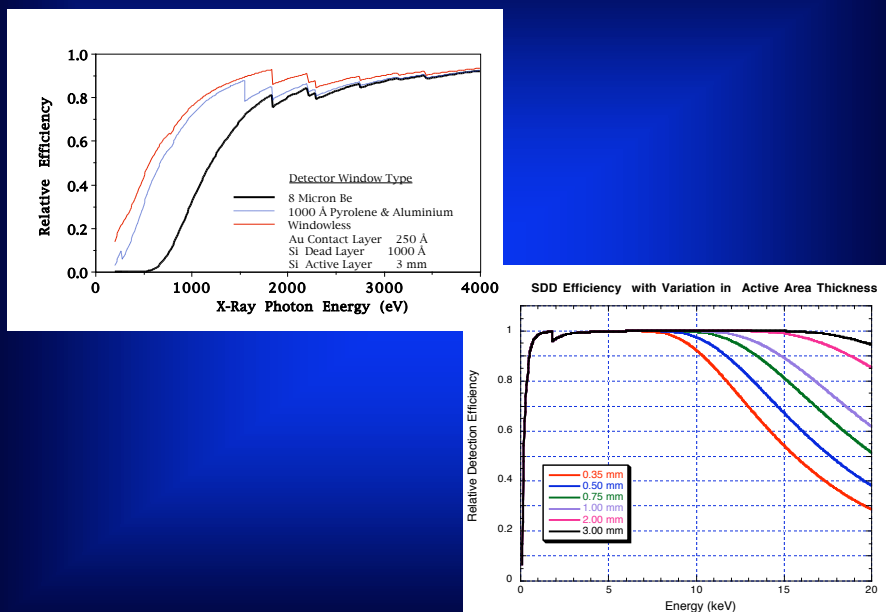
Electron Damage Effects



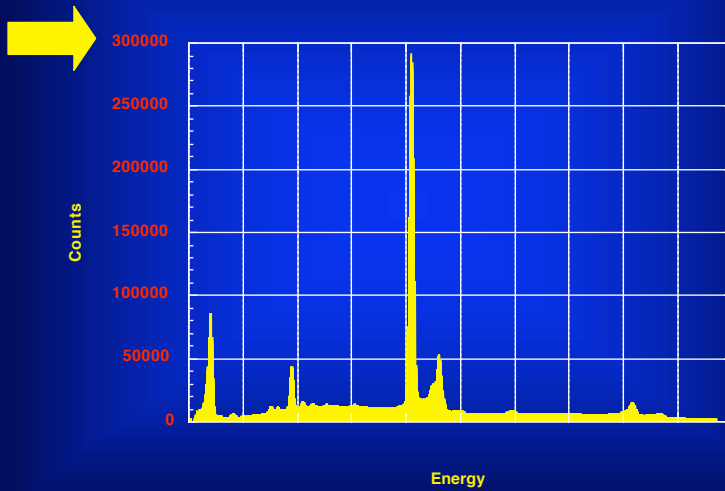
The Effects of Electron Irradiation



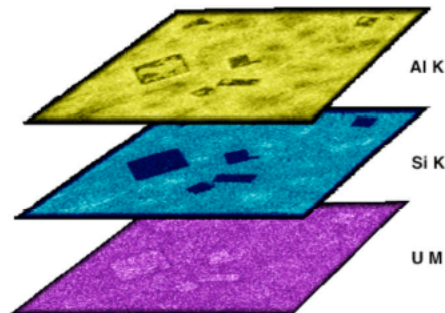
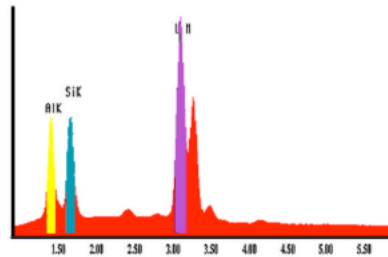
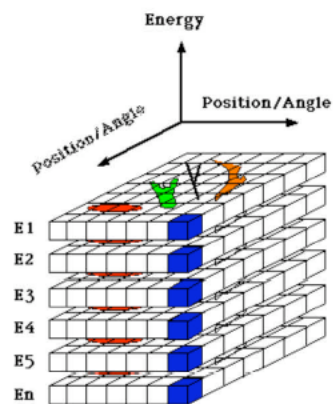
Relative Detector Efficiency

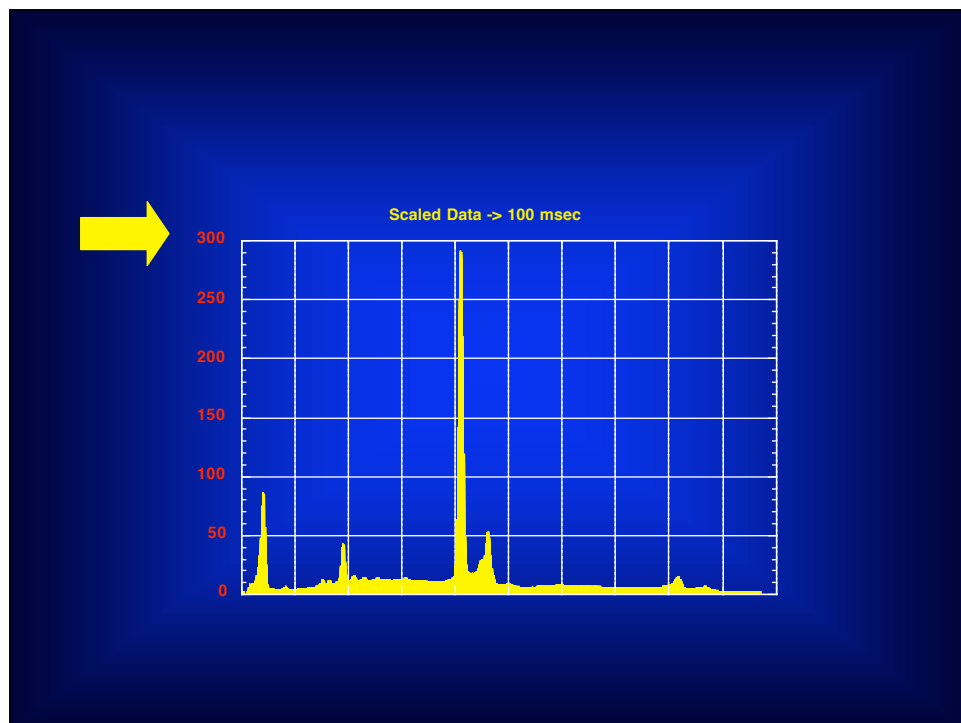
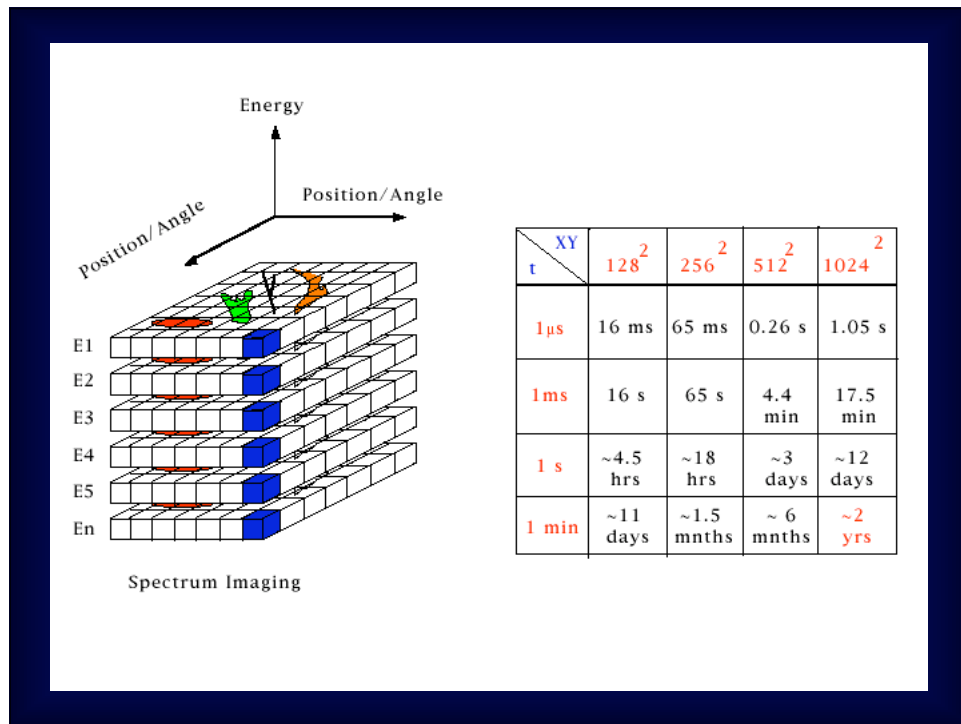


*Count Rate = ~ 200 Kcps
Time = 100 sec
Integral = 50, 000, 000 counts !*



Spectrum Imaging





Thanks
Questions?